OKI semiconductor MSM5128-20GSK

2048-WORD x 8-BIT C-MOS STATIC RAM (E3-S-013-32)

GENERAL DESCRIPTION

The MSM5128GS is a 2048-word by 8-bit CMOS static RAM featuring 5V power supply operation and direct TTL input/output compatibility. Since the circuitry is completely static, external clock and refreshing operations are unnecessary, making this device very easy to use. The MSM5128GS is also a CMOS silicon gate device which requires very little power during standby (maximum standby current of 50µA) when there is no chip selection. Stored data is retained if the power voltage drops to 2V, thereby enabling battery back-up.

A byte system is adopted, and since there is pin compatibility with standard ultra-violet EPROMs, this device is ideal for use as a peripheral memory for microcomputers and data terminal units etc. In addition, CS and OE signals enable OR ties with the output terminals of other chips, thereby facilitating simple memory expansion and bus line control etc.

FEATURES

- Single 5V Supply
- Battery Back-up at 2V
- Operating temperature range Ta = -40°C to +85°C
- Low Power Dissipation

Standby; 1.0 μ A MAX Ta = 25°C 10 μ A MAX Ta = 60°C 50 μ A MAX Ta = 85°C Operation; 200 mW TYP

- High Speed (Equal Access and Cycle Time) MSM5128-20; 200 ns MAX
- Direct TTL Compatible. (Input and Output)
- 3-State Output
- 24 Pin Flat PKG



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TRUTH TABLE

Mode	CS	WE	OE	I/O Operation
andby	н	×	x	High Z
	L	н	н	High Z
ead	L	н	L	DOUT
Vrite	L	L	×	DIN

X : H or L

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit	Conditions	
Supply Voltage	Vcc	-0.3 to 7.0	v		
Input Voltage	VIN	-0.3 to V _{CC} + 0.3	v	Respect to GNI	
Operating Temperature	Topr	-40 to 85	°C		
Storage Temperature	T _{stg}	-55 to 150	°C		
Power Dissipation	PD	1.0	w	Ta = 25°C	

RECOMMENDED OPERATING CONDITION

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Supply Voltage	Vcc	4.5	5	5.5	v	5V ± 10%
Supply Voltage	V _{SS}		0		v	
Data Retention Voltage	∨ссн	2	5	5.5	v	
	⊻ін	2.2		V _{CC} + 0.3	v	- 5V ± 10%
Input Voltage	VIL	-0.3		0.8	v	
Output Load	CL			100	рF	
Output Load	TTL			1		1

DC CHARACTERISTICS

Parameter		Cumbral		MSM5128-20				
raiameter	Symbol		Min.	Тур.	Max.	Unit	Test Condition	
Input Leakage Current	1	LI	-1		1	μА	VIN = 0 to VCC	
Qutput Leakage Current	I I	.0	-1		1	μА	$\overline{CS} = V_{ H} \text{ or}$ $\overline{OE} = V_{ H}$ $V_{I/O} = 0 \text{ to } V_{CC}$ $I_{OH} = -1 \text{ mA}$ $I_{OL} = 2.1 \text{ mA}$	
	V	ЭН	2.4			V		
Output Voltage	V	OL			0.4	v		
		Ta 25°C		0.1	1.0		Ξ.	
Standby Supply	'ccs	60° C			10	μA	1 -	CC - 0.2V 0 to VCC
Current		85° C			50	1		
	'co	CS1		0.3	1	mA	CS = V _{IH} t _{cyc} = Min. cycle	
Operating				35	50	mA	Min.	Ta = 0 ~ 85° C
Supply Current	ICCA			35	60	mA	cycle	Ta = -40 ~ 85°C

 $(V_{cc} = 5V \pm 10\%, T_a = -40^{\circ}C \text{ to } +85^{\circ}C)$

AC CHARACTERISTICS

Test Condition

Parameter	Conditions		
Input Pulse Level	VIH=2.2V, VIL=0.8V		
Input Rise and Fall Times	10 ns		
Input and Output Timing Reference Level	1.5V		
Output Load	CL=100 pF, 1 TTL Gate		

READ CYCLE

 $(V_{cc} = 5V \pm 10\%, T_a = -40^{\circ}C \text{ to } +85^{\circ}C)$

-		MSM5128-20		Unit
Parameter	Symbol	Min.	Max.	Unit
Read Cycle Time	tRC	200		ns
Address Access Time	^t AC	i	200	ns
Chip Select Access Time	tco		200	ns
Output Enable to Output Valid	tOE		120	ns
Chip Selection to Output Active	tCX	20		ns
Output Hold Time from Address Change	tOHA	20		ns
Output 3-state from Deselection	totd	0	60	ns

READ CYCLE



WRITE CYCLE

 $(V_{cc} = 5V \pm 10\%, T_a = -40^{\circ}C \text{ to } +85^{\circ}C)$

Deverse	Question	MSM5128-20		11-14	
Parameter	Symbol	Min.	Max.	Unit	
Write Cycle Time	twc	200		ns	
Address to Write Setup Time	tAS	20		ns	
Write Time	tw	120		ns	
Write Recovery Time	twR	20		ns	
Data Setup Time	tDS	80		ns	
Data Hold from Write Time	tDH	10		ns	
Output 3-State from Write	totw		60	ns	

Notes: 1. A Write Cycle occurs during the overlap of a low CS and a low WE.

2. OE may be both high and low in a Write Cycle.

3. tAS is specified from CS or WE, whichever occurs last.

4. tw is an overlap time of a low CS and a low WE.

5. tWR, tDS and tDH are specified from CS or WE, whichever occurs first.

6. torw is specified by the time when DATA OUT is floating, not defined by output level.

7. When I/O pins are Data output mode, don't force inverse signal to those pins.

WRITE CYCLE



LOW VCC DATA RETENTION CHARACTERISTICS

 $(T_a = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted})$

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
V _{CC} for Data Retention	Vссн	2			V	VIN = OV to VCC, CS = VCC
Data Retention Current	1ссн		0.05	20	μA	$V_{CC} = 2V \overline{CS} = V_{CC}$ $V_{IN} = 0V \text{ to } V_{CC}$
CS to Data Retention Time	⁺su	0			ns	
Operation Recovery Time	tR	tRC			ns	



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CAPACITANCE

 $(Ta = 25^{\circ}C, f = 1 MHz)$

Parameter	Symbol	Min.	Тур.	Max.	Unit
Input/Output Capacitance	CI/O			8	pF
Input Capacitance	CIN			6	pF

Note: This parameter is periodically sampled and not 100% tested.